Section I (Listing of the Claims)

Please amend claims 1, 10, 12-18 and 20, cancel claim 9, and add new claims 21-28, as set out in the listing of pending claims 1-28 of the application below.

1. **(Currently amended)** A method comprising:

heating a polytetrafluoroethylene material to an elevated temperature; [[and]]

maintaining said heating for a time sufficient to substantially reduce a particle count character of the polytetrafluoroethylene material;

fabricating a finished article comprising the polytetrafluoroethylene material; and

contacting at least one surface of the finished article comprising the polytetrafluoroethylene material with a substance substantially free of contaminants.

2. **(Original)** The method of claim 1 further comprising applying a melting temperature to a portion of the polytetrafluoroethylene material for welding thereof prior to said heating.

3. **(Previously presented)** The method of claim 2 wherein the melting temperature is within about 15°C of a melting point of the polytetrafluoroethylene material.

4. **(Original)** The method of claim 2 wherein said applying forms a heat affected zone of the portion, said heating and said maintaining to affect the heat affected zone.

5. **(Previously presented)** The method of claim 1 wherein the elevated temperature is above a glass transition temperature of the polytetrafluoroethylene material.

6. **(Original)** The method of claim 1 wherein the elevated temperature is between about 130°C and about 260°C.

7. **(Original)** The method of claim 1 wherein the time is between about 20 hours and about 100 hours.

8. **(Previously presented)** The method of claim 1 wherein said maintaining occurs in a periodic manner comprising:

cooling the polytetrafluoroethylene material; and

reheating the polytetrafluoroethylene material.

9. **(Canceled)**

10. **(Currently amended)** A method comprising:

heating a polytetrafluoroethylene material to about 228°C for a sufficient time to substantially reduce a particle count character thereof;

fabricating a finished article comprising the polytetrafluoroethylene material; and

contacting at least one surface of the finished article comprising the polytetrafluoroethylene material with a substance substantially free of contaminants.

11. **(Original)** The method of claim 10 wherein said heating is for about 100 hours.

12. **(Currently amended)** A container adapted to store and dispense at least one substantially contaminant-free substance, the container comprising a polytetrafluoroethylene material having a particle count character reduced by application of an elevated temperature thereto.

13. **(Currently amended)** The container ~~polytetrafluoroethylene material~~ of claim 12 wherein the elevated temperature is between about 130° and about 260°C.

14. **(Currently amended)** The container ~~polytetrafluoroethylene material~~ of claim 12 wherein the application of the elevated temperature is for between about 20 hours and about 100 hours.

15. **(Currently amended)** The container ~~polytetrafluoroethylene material~~ of claim 12 wherein the elevated temperature is about 228°C and the application is for about 100 hours.

16. **(Currently amended)** The container ~~polytetrafluoroethylene material~~ of claim 12 ~~in the form of~~ wherein the polytetrafluoroethylene material comprises a film ~~for contacting a substance~~.

17. **(Currently amended)** The container ~~polytetrafluoroethylene material~~ of claim 12[[16]] wherein the substance comprises any ~~is one~~ of a liquid and a powder.

18. **(Currently amended)** The container ~~polytetrafluoroethylene material~~ of claim 17 wherein the container comprises a liner adapted to contact the substance, and the liner comprises the polytetrafluoroethylene film ~~is incorporated in a package to contain the substance~~.

19. **(Withdrawn)** A method of determining a temperature and time at which heat processible polytetrafluoroethylene (PTFE) fluoropolymer films are heat-treatable to reduce particle count thereof, comprising:

providing a set of heat processible PTFE fluoropolymer films;

subjecting each film of said set of heat processible PTFE fluoropolymer films to a predetermined temperature for a predetermined time of heat processing, wherein temperature and time of heat processing are varied among films in said set, to provide a range of heat processing temperatures and a range of heat processing times for heat processed films in said set;

after said heat processing, determining particle counts for the heat processed films in said set;

performing regression analysis on the particle counts to determine temperature and heat processing time at which particle count is minimized, as said determined temperature and time.

20. **(Withdrawn)** A method ~~of treating a polytetrafluoroethylene film to reduce particle count character thereof,~~ comprising:

exposing a polytetrafluoroethylene [[the]] film to a temperature in a range of from about 150°C to about 250°C for a time greater than 20 hours, sufficient to reduce particle count of said film to below 10 particles/ml of particles having a diameter of 0.2 micron;

fabricating a finished article comprising the polytetrafluoroethylene film; and

contacting at least one surface of the finished article comprising the polytetrafluoroethylene film with a substance substantially free of contaminants.

21. **(New)** The method of claim 1, wherein the polytetrafluoroethylene material with which the finished article is fabricated is substantially non-shedding.

22. **(New)** The method of claim 1, wherein the polytetrafluoroethylene material comprises a film.

23. **(New)** The method of claim 22, wherein said fabricating includes welding at least a portion of the film.

24. **(New)** The method of claim 1, wherein the finished article comprises any of a chemical storage container and a liner for a chemical storage container.

25. **(New)** The method of claim 1, wherein the substance comprises a semiconductor processing substance.

26. (New) The method of claim 1, further comprising the step of analyzing at least a portion of the substance for the presence of PTFE particles, wherein said analyzing is performed after said contacting.

27. (New) The method of claim 1, wherein said fabricating is performed after said heating.

28. (New) The container of claim 12 wherein the substance comprises a semiconductor processing substance.